

General Description

The ZM031N04D combines advanced trench MOSFET technology with a low resistance package to provide extremely low $R_{DS(ON)}$.

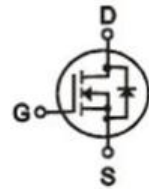
Features

- Advance high cell density Trench technology
- Low $R_{DS(ON)}$ to minimize conductive loss
- Low Gate Charge for fast switching
- Low Thermal resistance

Application

- MB/VGA Vcore
- SMPS 2nd Synchronous Rectifier
- POL application
- BLDC Motor driver

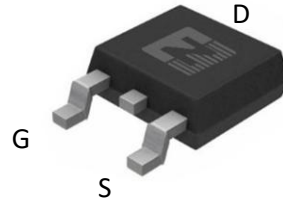
Product Summary



$$V_{DS}=40V$$

$$R_{DS(ON)} = 2.9m\Omega$$

$$I_D=120A$$



TO-252

Ordering Information:

Part NO.	ZM031N04D
Marking	ZM031N04
Packing Information	REEL TAPE
Basic ordering unit (pcs)	2500

Absolute Maximum Ratings ($T_c = 25^\circ C$)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	40	V
Gate-Source Voltage	V_{GS}	± 20	V
Continuous Drain Current	$I_{D@TC=25^\circ C}$	120	A
	$I_{D@TC=75^\circ C}$	91.2	A
	$I_{D@TC=100^\circ C}$	75.6	A
Pulsed Drain Current ^①	I_{DM}	280	A
Total Power Dissipation($TC=25^\circ C$)	$P_{D@TC=25^\circ C}$	70	W
Total Power Dissipation($TA=25^\circ C$)	$P_{D@TA=25^\circ C}$	2.5	W
Operating Junction Temperature	T_J	-55 to 150	$^\circ C$
Storage Temperature	T_{STG}	-55 to 150	$^\circ C$
Single Pulse Avalanche Energy@ $L=0.1mH$	E_{AS}	180	mJ
Avalanche Current@ $L=0.1mH$	I_{AS}	60	A

●Thermal resistance

Parameter	Symbol	Min.	Typ.	Max.	Unit
Thermal resistance, junction - case	R_{thJC}	-	-	2.1	°C/W
Thermal resistance, junction - ambient	R_{thJA}	-	-	65	°C/W
Soldering temperature, wave soldering for 10s	T_{sold}	-	-	265	°C

●Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=250\mu A$	40			V
Gate Threshold Voltage	$V_{GS(TH)}$	$V_{GS}=V_{DS}, I_D=250\mu A$	1.2		2.5	V
Drain-Source Leakage Current	I_{DSS}	$V_{DS}=40V, V_{GS}=0V$			1.0	μA
Gate- Source Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$			± 100	nA
Static Drain-source On Resistance	$R_{DS(ON)}$	$V_{GS}=10V, I_D=24A$		2.9	4	m Ω
		$V_{GS}=4.5V, I_D=12A$		3.9	5.5	m Ω
Forward Trans conductance	g_{FS}	$V_{DS}=25V, I_D=10A$		16		S
Source-drain voltage	V_{SD}	$I_S=24A$			1.28	V

●Electronic Characteristics

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Input capacitance	C_{iss}	f = 1MHz V _{DS} =25V	-	4800	-	pF
Output capacitance	C_{oss}		-	460	-	
Reverse transfer capacitance	C_{rss}		-	240	-	

●Gate Charge characteristics(T_a = 25°C)

Parameter	Symbol	Condition	Min.	Typ	Max.	Unit
Total gate charge	Q_g	V _{DD} =25V I _D = 20A V _{GS} = 10V	-	55	-	nC
Gate - Source charge	Q_{gs}		-	12	-	
Gate - Drain charge	Q_{gd}		-	15	-	

Note: ① Pulse Test : Pulse width ≤ 300μs, Duty cycle ≤ 2% ;

Fig.1 Power Dissipation

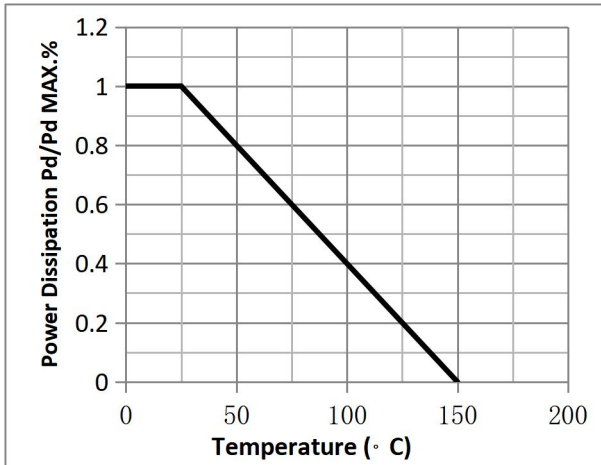


Fig.2 Typical output Characteristics

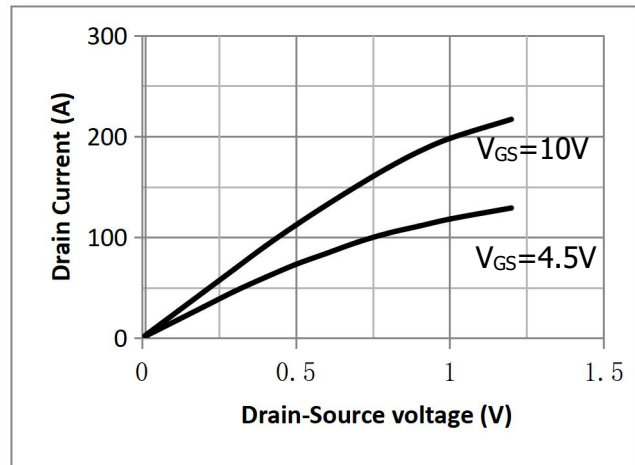


Fig.3 Threshold Voltage V.S Junction Temperature

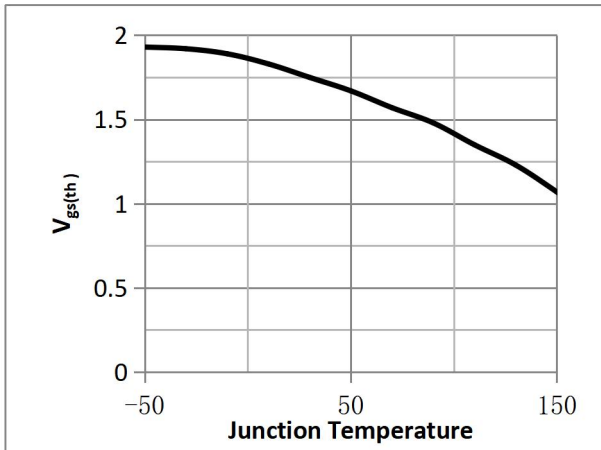


Fig.4 Resistance V.S Drain Current

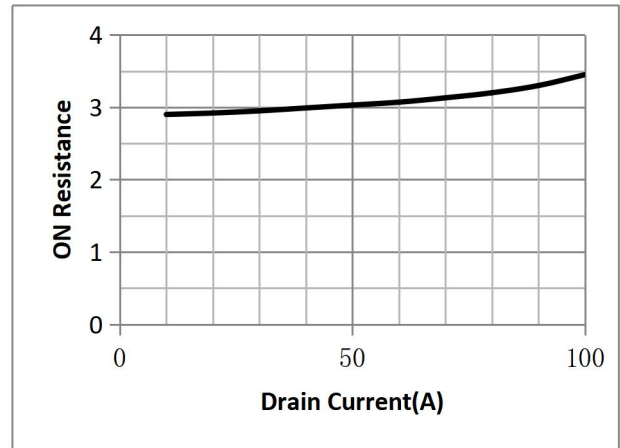


Fig.5 On-Resistance VS Gate Source Voltage

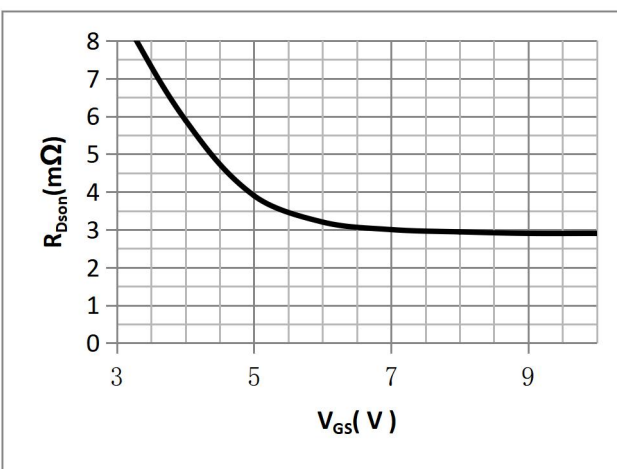


Fig.6 On-Resistance V.S Junction Temperature

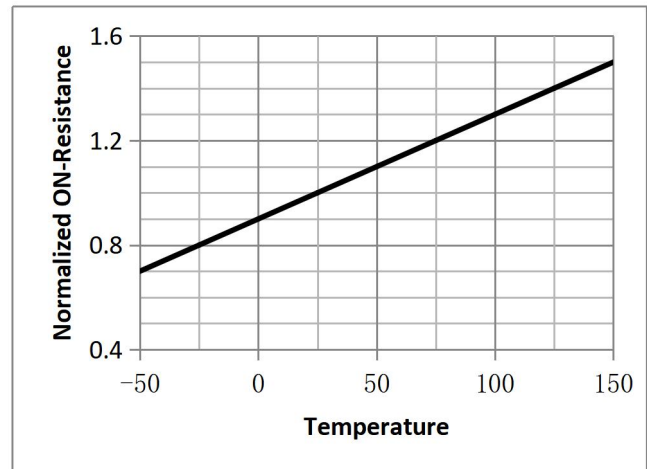


Fig.7 Switching Time Measurement Circuit

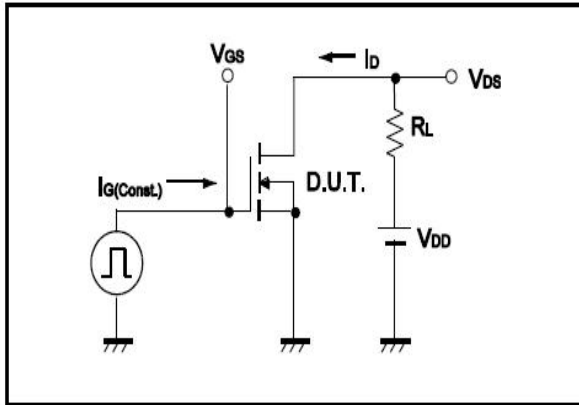


Fig.8 Gate Charge Waveform

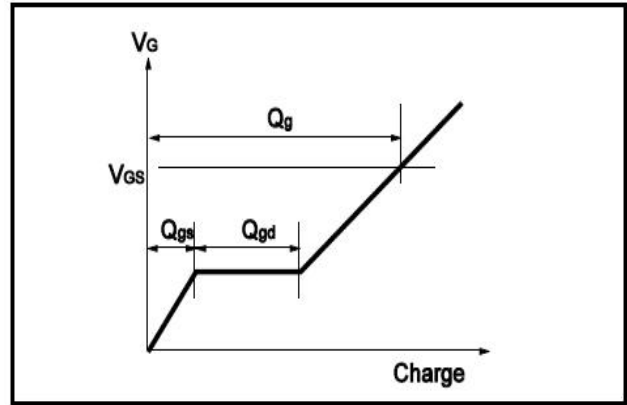


Fig.9 Switching Time Measurement Circuit

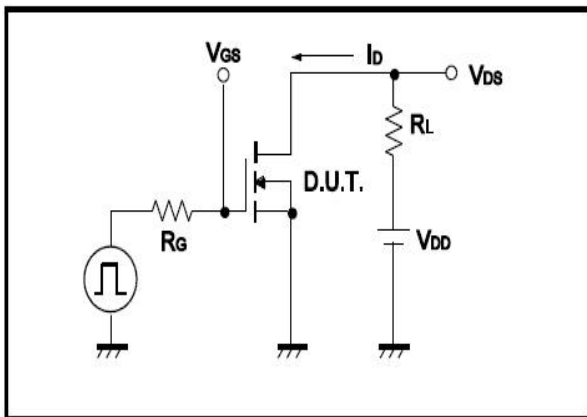


Fig.10 Gate Charge Waveform

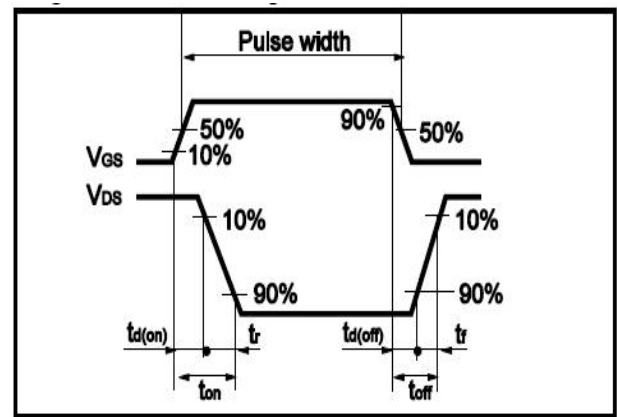


Fig.11 Avalanche Measurement Circuit

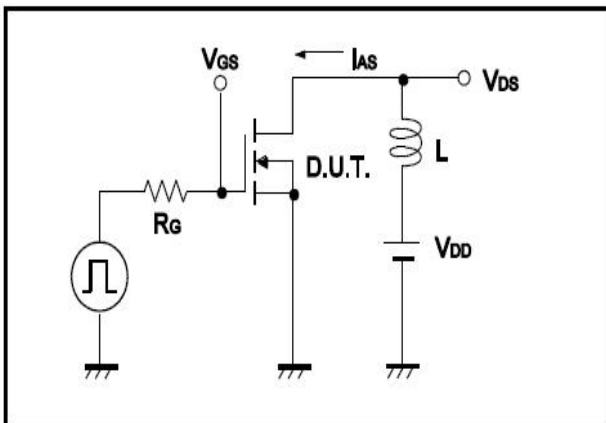
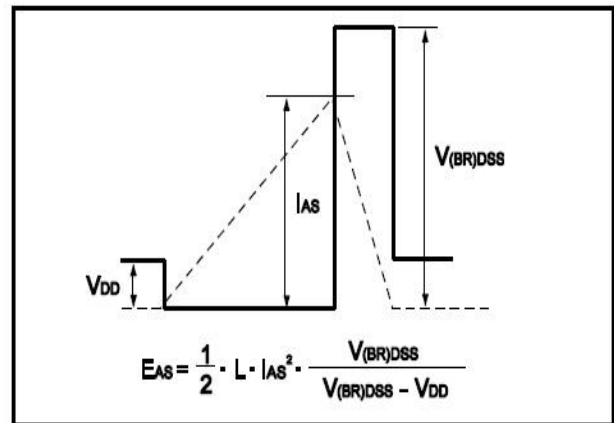


Fig.12 Avalanche Waveform



**•Dimensions (TO-252)**

Unit: mm

SYMBOL	min	max	SYMBOL	min	max
A	2.10	2.50	B	0.85	1.25
b	0.50	0.80	b1	0.50	0.90
b2	0.45	0.70	C	0.45	0.70
D	6.30	6.75	D1	5.10	5.50
E	5.30	6.30	e1	2.25	2.35
L1	9.20	10.60	e2	4.45	4.75
L2	0.90	1.75	L3	0.60	1.10
K	0.00	0.23			

